

Abstract

The aim of the invention is to simplify and improve the production method for circuit arrangements that are mounted on a support element or carrier body (5). The support element (5) has thermal lead-through contacts (7) which are at least partially closed by a screen printing process. To this end, the screen printing process is carried out after the application of a first metallization layer (6) to the support element (5), whereby the first layer forms the base metallization. Residue of the screen printing material (8) protruding on the underside (13) of the support element (5) is removed once the screen printing material (8) has been cured. The removal is performed by using at least a mechanical cleaning process and/or a chemical cleaning process.